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Part Number: [0465531200](#)
Status: **Active**
Description: 1.20mm (.047") x 2.00mm (.079") Pitch HD Mezz™ Receptacle, 104 Circuits, 18.00mm (.708") Unmated Height, 11 Rows, Selectively Filled, Lead Free

Documents:

[3D Model](#) [Product Specification PS-45802-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	PCB Receptacles
Series	46553
Application	Board-to-Board
Comments	1.20mm (.047") Pitch Pin-to-Pin and 2.00mm (.079") Pitch Row-to-Row
Product Name	Mezzanine

Physical

Circuits (Loaded)	104
Circuits (maximum)	104
Color - Resin	Black
Durability (mating cycles max)	100
Glow-Wire Compliant	No
Guide to Mating Part	No
Keying to Mating Part	None
Lock to Mating Part	Yes
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Rows	11
Orientation	Vertical
PC Tail Length (in)	0.000 In
PC Tail Length (mm)	0.00 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.000 In
PCB Thickness Recommended (mm)	0.00 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Robotic Placement	Vacuum Pick-Up Tape
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Surface Mount

Electrical

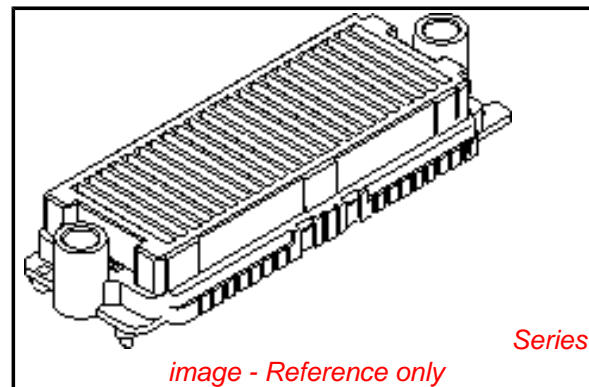


image - Reference only

EU RoHS

ELV and RoHS Compliant
REACH SVHC
 Not Reviewed
Halogen-Free
Status

China RoHS



Not Reviewed

Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

46553Series

Current - Maximum	2A
Grounding to PCB	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	20
Lead-free Process Capability	Reflow Capable (SMT only)
Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

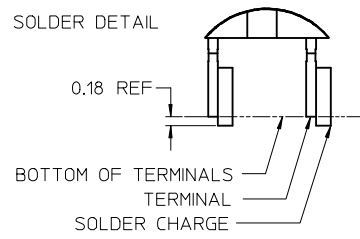
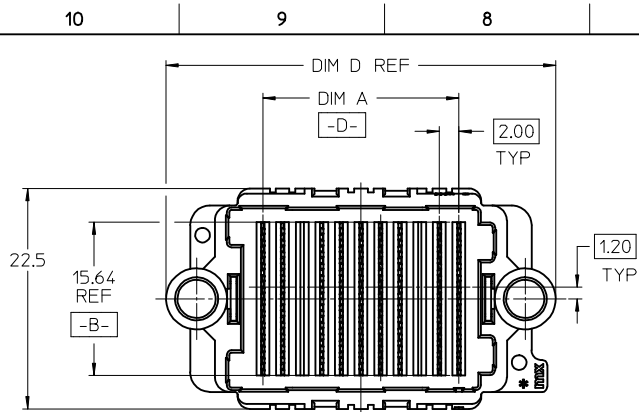
Material Info

Reference - Drawing Numbers

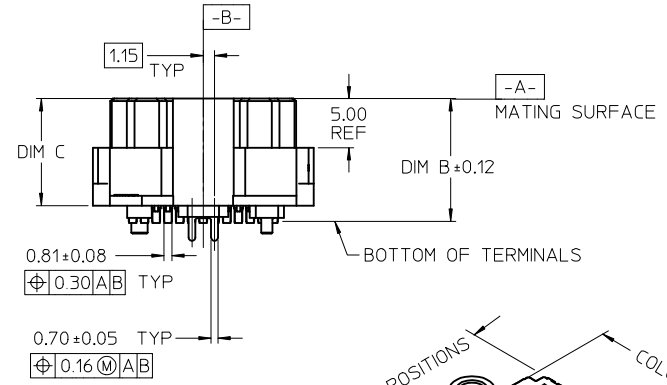
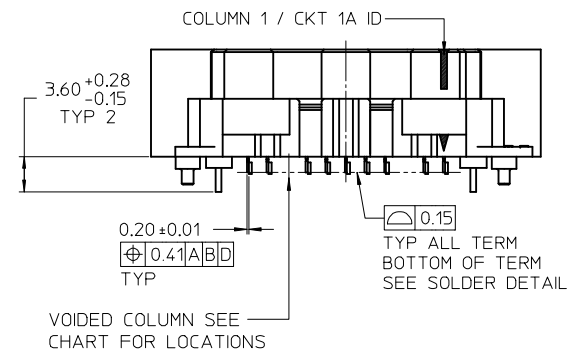
Product Specification	PS-45802-001
Sales Drawing	SD-46553-001

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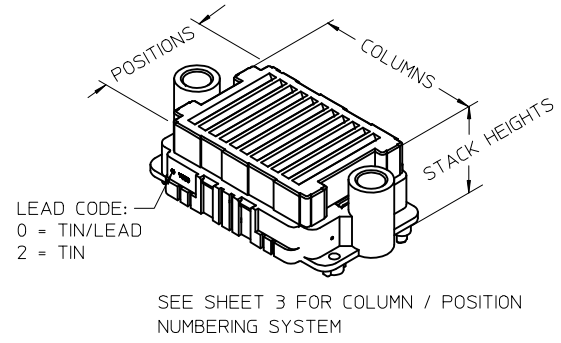
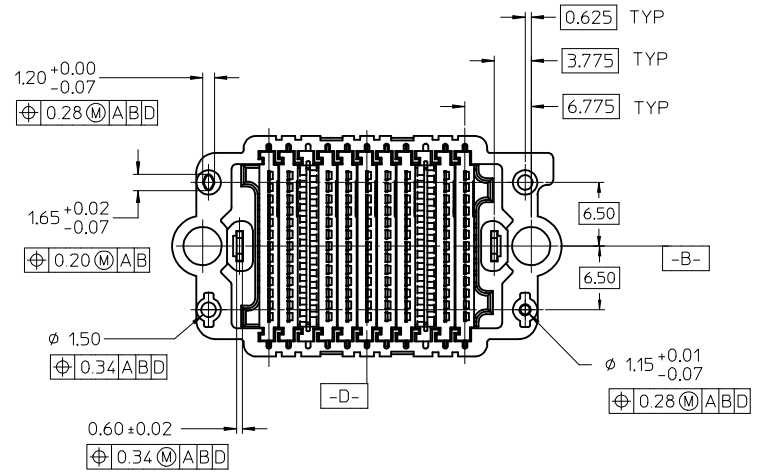


- NOTES:
- HOUSING MATERIAL: LCP, GLASS FILLED, UL 94V-0, BLACK
CONTACT MATERIAL: HIGH PERFORMANCE ALLOY
SOLDER NAIL MATL: STAINLESS STEEL
SOLDER CHARGE MATL: SEE CHART
 - FINISH: SELECT GOLD 30 MI MIN IN CONTACT AREA
SELECT TIN: 100 MI MIN IN PCB TAIL BOTH OVER NICKEL
 - PRODUCT SPECIFICATION: PS-45802-001
 - COSMETIC SPECIFICATION, PS-45499-002 CLASS B
 - PACKAGING SPECIFICATION: PK-45802-001
 - DATUM -D- IS THE CENTERLINE OF THE 2 END SLOTS. END SLOT CENTERLINES ARE ESTABLISHED USING 2 MEASUREMENTS FOR EACH SLOT TAKEN 7.20 EITHER SIDE OF DATUM -B-.



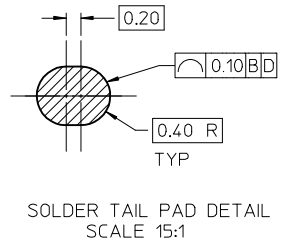
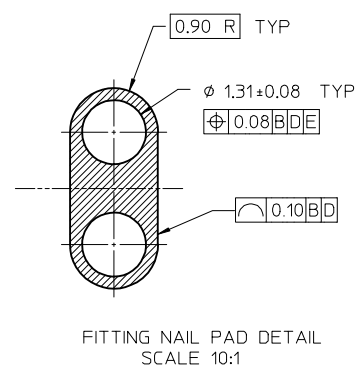
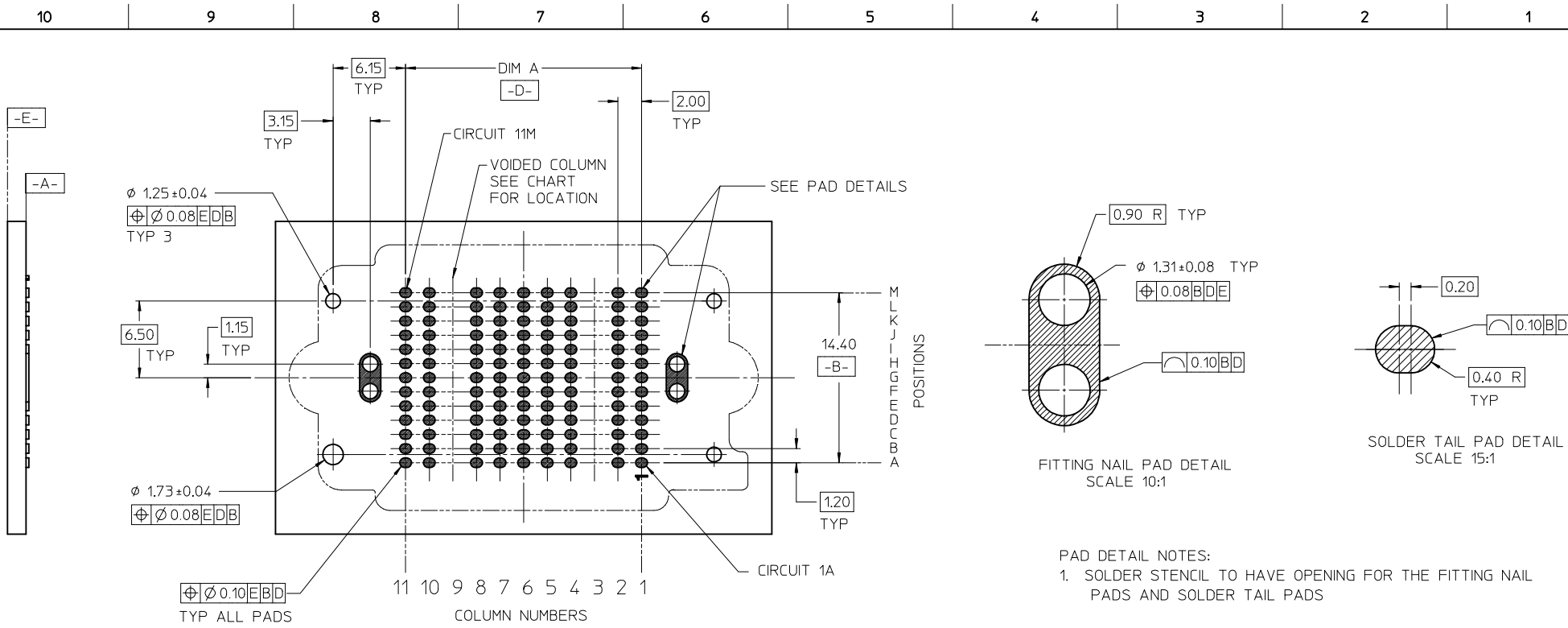
AVAILABLE STACK HEIGHTS		
STACK HEIGHT	DIM B	DIM C
8mm	10.51	8.90
9mm	11.51	9.90
10mm	12.51	10.90
11mm	13.51	11.90
12mm	14.51	12.90
13mm	15.51	13.90
14mm	16.51	14.90
15mm	17.51	15.90
17mm	19.51	17.90
18mm	20.51	18.90

AVAILABLE COLUMNS		
NO OF COLUMNS	DIM A	DIM D
7	12.00	31.89
9	16.00	35.89
11	20.00	39.89
13	24.00	43.89
15	28.00	47.89
17	32.00	51.89
19	36.00	55.89
21	40.00	59.89
23	44.00	63.89
25	48.00	67.89
27	52.00	71.89



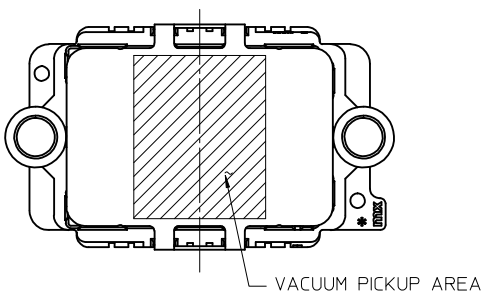
SEE SHEET 3 FOR COLUMN / POSITION NUMBERING SYSTEM

ADD OPTIONS EC NO: UCP2009-2695 DRWNR: RHODGE CHKD: 2009/05/15 APPR: JCOMERCI 2009/05/15	QUALITY SYMBOLS DESCRIPTION REV B1	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± 0.10 ± --- 2 PLACES ± 0.15 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1/2°	DIMENSION STYLE MM ONLY DRAWN BY DATE RHODGE 2007/05/31 CHECKED BY DATE RHODGE 2007/11/13 APPROVED BY DATE JCOMERCI 2007/11/14 MATERIAL NO. SEE CHART	SCALE 2:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE HIGH DENSITY MEZZININE RECEPTACLE ASSEMBLY SELECTIVELY LOADED MOLEX INCORPORATED DOCUMENT NO. SD-46553-001 SHEET NO. 1 OF 3
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



PAD DETAIL NOTES:
 1. SOLDER STENCIL TO HAVE OPENING FOR THE FITTING NAIL PADS AND SOLDER TAIL PADS

RECOMMENDED PCB LAYOUT: COMPONENT SIDE
 PCB THICKNESS: NA
 (11 COLUMN PART SHOWN SEE CHART)



SEE SHEET 1 EC NO: UCP2009-2695 DRAWN: RHODGE 2009/05/14 CHKD: 2009/05/15 APPR: JCOMERCI 2009/05/15 REV B1	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY RHODGE	DATE 2007/05/31	TITLE HIGH DENSITY MEZZININE RECEPTACLE ASSEMBLY SELECTIVELY LOADED		
	4 PLACES	± ---	± ---	CHECKED BY RHODGE	DATE 2007/11/13			
	3 PLACES	± 0.10	± ---	APPROVED BY JCOMERCI	DATE 2007/11/14	MOLEX INCORPORATED		
	2 PLACES	± 0.15	± ---	MATERIAL NO.	SEE CHART			
1 PLACE	± 0.25	± ---	ANGULAR ±1/2°		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

